

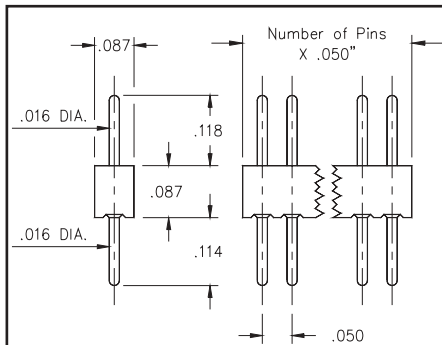


Fig. 1

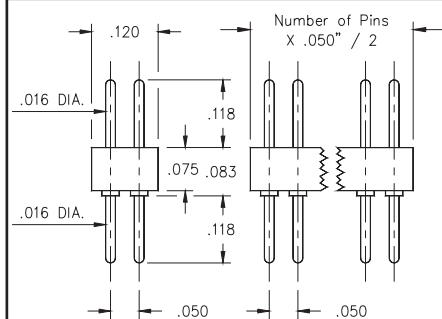


Fig. 2

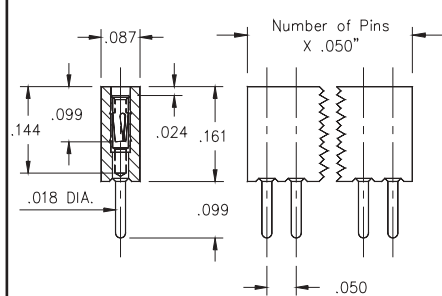


Fig. 3

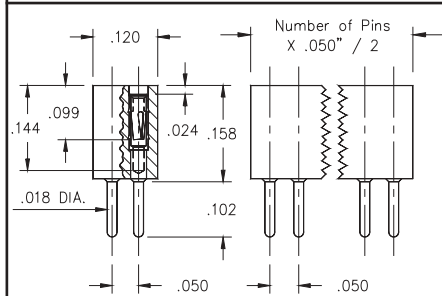


Fig. 4

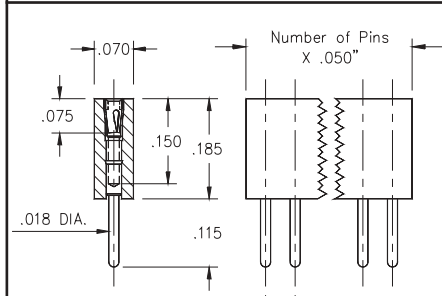
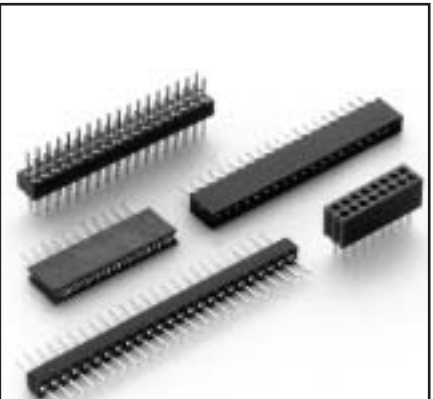


Fig. 5

- Series 850 single and double row interconnects have .050" pin spacing and permit board stacking as low as .248".
- Pin headers have .017" dia. pins. (MM# 3006 see page 166 for details).
- MM# 0489 and 0467 receptacles use M-M#11 Hi-Rel, 3-finger beryllium copper contacts rated at 3 amps. (#11 contact accepts pin diameters from .015-.020)
- Insulators are high temp. thermo-plastic, suitable for all soldering operations.



Ordering Information

Fig. 1	Single Row .087" Profile Pin Header			
	850-XX-0__-10-001 Specify # of pins  01-50			
Fig. 2	Double Row .075" Profile Pin Header			
	852-XX-__-10-001 Specify # of pins  002-100			
 XX= Plating Code See Below				
SPECIFY PLATING CODE XX=		10	90	
Pin Plating		10μ" Au	200μ" Sn/Pb	
Fig. 3	Single Row .161" Profile Socket			
	851-XX-0__-10-001 Specify # of pins  01-50			
Fig. 4	Double Row .161" Profile Socket			
	853-XX-__-10-001 Specify # of pins  002-100			
Fig. 5	Single Row .185" Profile Socket			
	851-XX-0__-10-002 Specify # of pins  01-77			
 XX= Plating Code See Below				
SPECIFY PLATING CODE XX=			93	99
Sleeve (Pin)			200μ" Sn/Pb	200μ" Sn/Pb
Contact (Clip)			30μ" Au	200μ" Sn/Pb